PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wei-Chun HUA	12/28/2010
Chung-Long CHANG	12/28/2010
Chun-Hung CHEN	12/28/2010
Chih-Ping CHAO	12/28/2010
Jye-Yen CHENG	01/03/2011
Hua-Chou TSENG	01/03/2011

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12984731

OP $40.00 12984731

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Benjamin J. Hauptman

Total Attachments: 2
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Docket No.: T5057-B361U

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1)	**Wei-Chun HUA**	4)	**Chih-Ping CHAO**
2)	**Chung-Long CHANG**	5)	**Jye-Yen CHENG**
3)	**Chun-Hung CHEN**	6)	**Hua-Chou TSENG**

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

PROTECTION STRUCTURE FOR METAL-OXIDE-METAL CAPACITOR

(a) for which an application for United States Letters Patent was filed on 1-5-2011, and identified by United States Patent Application No. 12/984,731 ; or

(b) for which an application for United States Letters Patent was executed on ___________,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) ✓ Wei-Chun Hua — ✓ Dec. 28, 2010
Name: **Wei-Chun HUA** — Date:

2) ✓ Chung-Long Chang — ✓ Dec/28 '2010.
Name: **Chung-Long CHANG** — Date:

3) ✓ Ch chen — ✓ Dec/28 '2010
Name: **Chun-Hung CHEN** — Date:

4) ✓ Chih-Ping Chao
Name: **Chih-Ping CHAO**

✓ Dec, 28. 2010
Date:

5) ✓ Jye Yen Cheng
Name: **Jye-Yen CHENG**

✓ Jan. 03, 2011
Date:

6) ✓ Hua-Chou Tseng
Name: **Hua-Chou TSENG**

✓ Jan/03/'11
Date: